### SUBMINIATURE SOLID STATE LAMP

Part Number: AM2520EJ/ID5V

High Efficiency Red

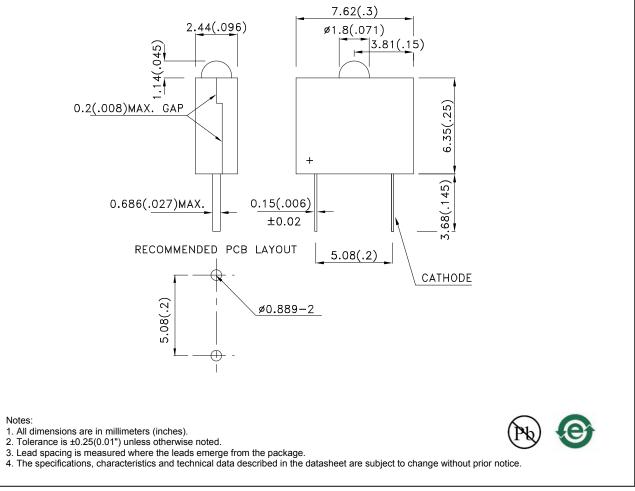
#### Features

- Black case enhances contrast.
- Vibration and shock resistant.
- 5V internal resistor.
- Housing UL rating:94V-0.
- Housing material: type 66 nylon.
- RoHS compliant.

#### Description

The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

#### Package Dimensions



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### Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] V= 5V		Viewing Angle [1]
			Min.	Тур.	201/2
AM2520EJ/ID5V	High Efficiency Red (GaAsP/GaP)	Red Diffused	4	12	40°
		Reu Dinuseu	*3	*8	

Notes:

1.  $\theta$ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

Luminous intensity/ luminous Flux: +/-15%.
\* Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

#### Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Ту	p.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	High Efficiency Red	627	*627		nm	VF=5V
λD [1]	Dominant Wavelength	High Efficiency Red	625	*617		nm	VF=5V
Δλ1/2	Spectral Line Half-width	High Efficiency Red	45			nm	VF=5V
lf	Forward Current	High Efficiency Red	1	3	17.5	mA	VF=5V
IR	Reverse Current	High Efficiency Red			10	uA	VR = 5V

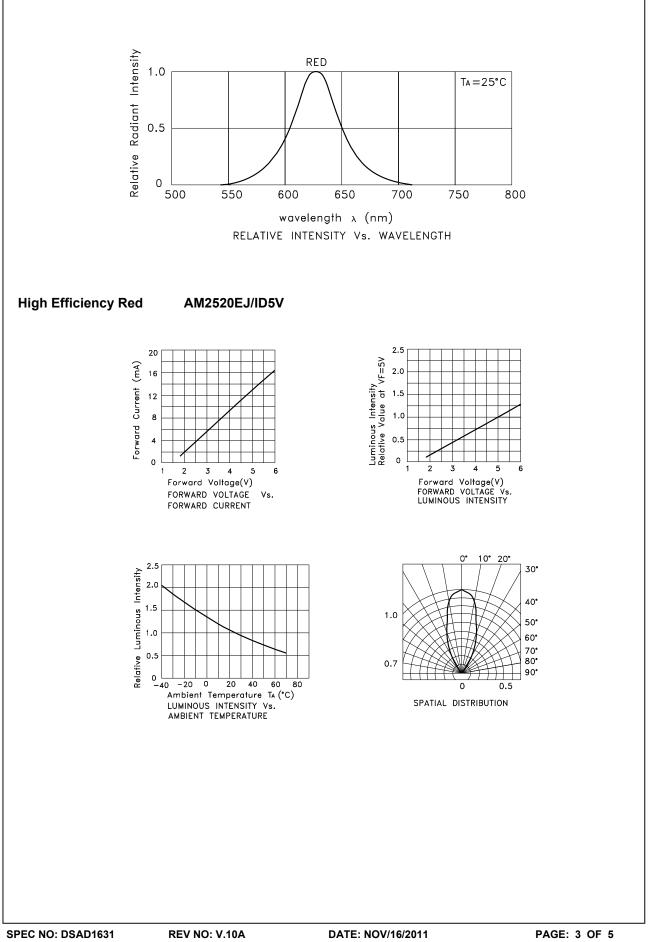
Note: 1.Wavelength: +/-1nm. \*Wavelength value is traceable to the CIE127-2007 compliant national standards.

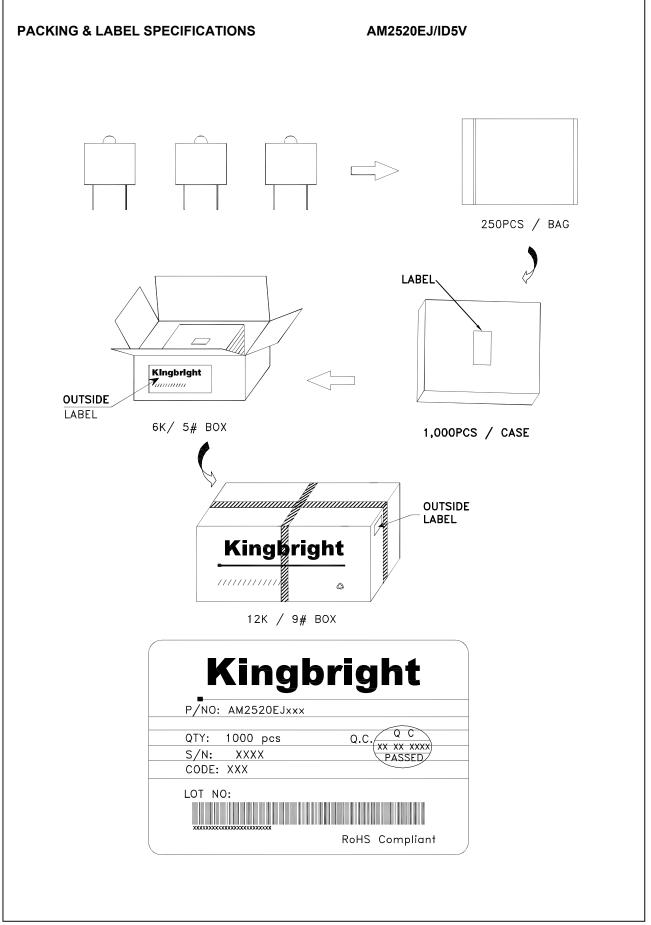
#### Absolute Maximum Ratings at TA=25°C

Parameter	High Efficiency Red	Units		
Power dissipation	85	mW		
Forward Voltage	6	V		
Reverse Voltage	5	V		
Operating Temperature	-40°C To +70°C			
Storage Temperature	-40°C To +85°C			
Lead Solder Temperature [1]	260°C For 3 Seconds			
Lead Solder Temperature [2]	260°C For 5 Seconds			

Notes:

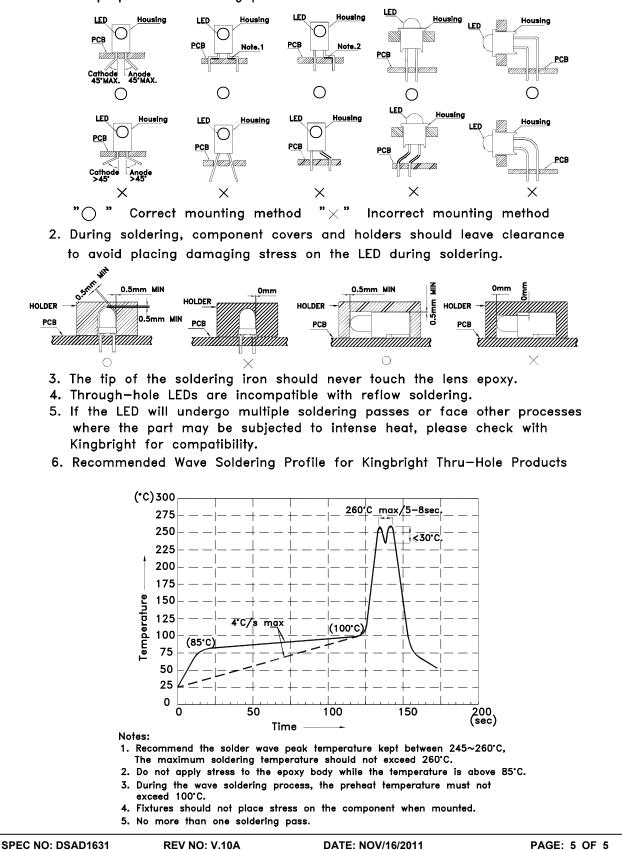
2. 5mm below package base.
2. 5mm below package base.





### PRECAUTIONS

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.



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